



Final Product Change Notification

201706002F01U01

Issue Date: 01-Sep-2017
Effective Date: 27-Nov-2017

UPDATE

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online



QUALITY

Change Category

Wafer Fab Process

Wafer Fab Materials

Wafer Fab Location

Assembly Process

Assembly Materials

Assembly Location

Product Marking

Mechanical Specification

Packing/Shipping/Labeling

Test Location

Test Process

Test Equipment

Design

Errata

Electrical spec./Test coverage

PCN UPDATE: MPC5777C Datasheet Update and New Part Number Introduction with Device Feature Revision and CSE Firmware Rev 2.08

Details of this Change

NXP Semiconductors is issuing an update to PCN_201706002F01 previously distributed on the 8-July-2017 to remove the part numbers with the Cryptographic Services Engine (CSE) security firmware to revision 2.08 previously listed in the affected part number list.

The following part numbers are removed from this notification:

SPC5777CAK3MME3
SPC5777CAK3MME3R
SPC5777CAK3MMO3
SPC5777CAK3MMO3R
SPC5777CDK3MME3
SPC5777CDK3MME3R
SPC5777CDK3MMO3
SPC5777CDK3MMO3R
SPC5777CLK3MME3
SPC5777CLK3MMO3
SPC5777CLK3MMO3R
SPC5777CRK3MME3
SPC5777CRK3MMO3
SPC5777CSK3MME3
SPC5777CSK3MME3R
SPC5777CSK3MMO3
SPC5777CSK3MMO3R

Why do we Implement this Change

The part numbers removed from this notification already have the Cryptographic Services Engine (CSE) security firmware revision 2.08 and are new part offerings which should be excluded from the affected parts list.

Identification of Affected Products

Product identification does not change
See Datasheet for part ordering summary.

Product Availability

Sample Information

Samples are available from 04-Aug-2017

Production

Planned first shipment 19-Sep-2017

Update Information

As described in sections under Details of This Change and Why do we Implement this Change.

Impact

Please see part number optional feature field in the datasheet for potential impact to product functionality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 01-Oct-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Peck Chuan Lee
Position Product Engineer
e-mail address peckchuan.lee@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP | Privacy Policy | Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Affected Part Numbers

SPC5777CK2MMO3

SPC5777CK2MME3

SPC5777CK3MME3

SPC5777CK3MMO3

SPC5777CK3MME3

SPC5777CK3MMO3